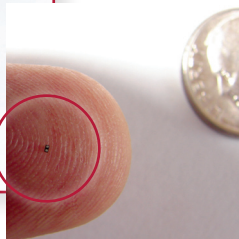
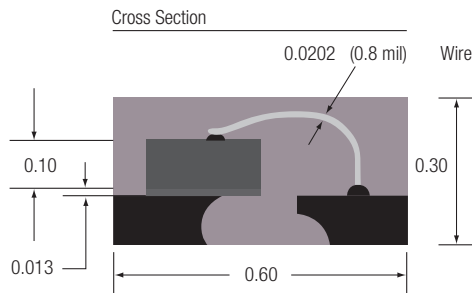
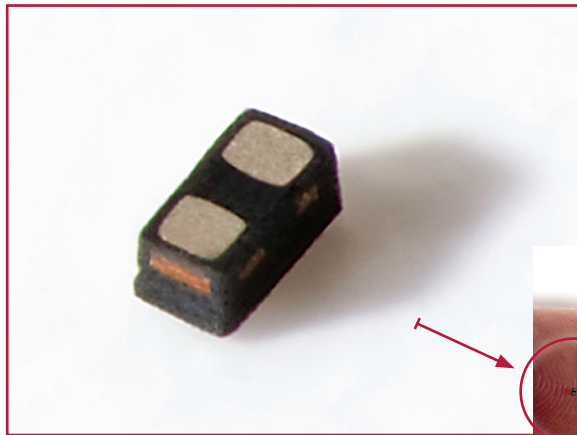


Extremely Thin MLP



Extremely Thin MLP

Carsem's "X3 Package Development Team" has created an extremely thin version of the MLP (Micro Leadframe Package). It is a two lead package with nominal dimensions of 0.6 mm long by 0.3 mm wide and 0.3 mm thick, which is very similar in size to a 0201 surface mount component. It will accept a nominal die size of 0.152 mm x 0.203 mm x 0.1 mm (6 mils x 8 mils x 3.9 mils) with a wire diameter of 0.0203 mm (0.8 mil).

The package is produced using Carsem's advanced MLP manufacturing capabilities including saw-singulation, which provides a package with precise square edges to assure easier handling during the printed circuit board manufacturing process. High-volume, full turn-key manufacturing services, including electrical testing, laser mark and tape-and-reel will begin during early 2010.

Carsem is currently in the process of registering the package outline with JEDEC's JC-11 Committee for Mechanical (Package Outlines) Standardization.

Applications:

The package was developed to primarily support the need for an effective solution to the manufacture of transient voltage suppression (TVS) diodes that are used to protect the electronic communication and consumer devices against electrostatic discharges (ESD). Additional package body size and lead count versions of the extremely thin MLP will be added in the near future.

Anyone interested in further details about this new package or would like to receive package samples should contact their local Carsem sales office.

Features:

- Nominal body size 0.6 mm long by 0.3 mm wide and 0.3 mm thick
- Similar in size to a 0201 surface mount component
- Nominal die size of 0.152 mm x 0.203 mm x 0.1 mm (6 mils x 8 mils x 3.9 mils)
- Wire diameter of 0.0203 mm (0.8 mil)
- Laser mark character size of 0.2 mm (7.9 mils)
- Full turn-key services including Final Test and Tape-and-Reel

Malaysia

Ipoh (M-site)
tel: 60-5-3123333
fax: 60-5-3125333

Malaysia

Ipoh (S-site)
tel: 60-5-5262333
fax: 60-5-5265333

China

Suzhou
tel: 86-512-6258-8883
fax: 86-512-6258-8885

Europe

UK
tel: 44-1793-853888
fax: 44-1793-853888

USA

Silicon Valley
tel: 831-438-6861
fax: 831-438-6863

USA

Los Angeles
tel: 626-854-0939
fax: 626-854-9139

USA

Dallas
tel: 972-580-1706
fax: 972-580-1806

USA

Boston
tel: 508-236-6070
fax: 508-236-6075

Taiwan

Taichung
tel: 886-917-210285

www.carsem.com
info@carsem.com

A Member of the
Hong Leong Group